Product Change Notification - JAON-28MDOD807

Date: 01 Dec 2016

Product Category: 16-bit Microcontrollers and Digital Signal Controllers

Notification subject: CCB 2699 Final Notice: Qualification of CuPdAu bond wire in selected products of the 0.25um TSMC wafer technology available in 64L QFN (9x9x0.9mm) package at MTAI assembly site.

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 64L QFN (9x9x0.9mm) package at MTAI assembly site.

Pre Change:
Using gold (Au) bond wire

Post Change:
Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI	MTAI
Wire material	Au wire	CuPdAu wire
Die attach material	3280	3280
Molding compound material	G700LTD	G700LTD
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:
In Progress

Estimated First Ship Date:
February 28, 2017 (Date code: 1708)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	December 2016						February 2017			
Workweek	48	49	50	51	52		05	06	07	08
Qual Report Availability	X									
Final PCN Issue Date	X									
Estimated Implementation Date										X

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
December 1, 2016: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-28MDOD807_Qual Report.pdf
PCN_JAON-28MDOD807_Affected CPN.pdf
PCN_JAON-28MDOD807_Affected CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-28MDOD807
CATALOG_PART_NBR
DSPIC33FJ128GP206A-E/MR
DSPIC33FJ128GP206A-I/MR
DSPIC33FJ128GP206AT-E/MR
DSPIC33FJ128GP206AT-I/MR
DSPIC33FJ128GP306A-E/MR
DSPIC33FJ128GP306A-I/MR
DSPIC33FJ128GP306AT-E/MR
DSPIC33FJ128GP306AT-I/MR
DSPIC33FJ128GP706A-E/MR
DSPIC33FJ128GP706A-H/MR
DSPIC33FJ128GP706A-I/MR
DSPIC33FJ128GP706AT-E/MR
DSPIC33FJ128GP706AT-H/MR
DSPIC33FJ128GP706AT-I/MR
DSPIC33FJ128MC506A-E/MR
DSPIC33FJ128MC506A-H/MR
DSPIC33FJ128MC506A-I/MR
DSPIC33FJ128MC506AT-E/MR
DSPIC33FJ128MC506AT-H/MR
DSPIC33FJ128MC506AT-I/MR
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DSPIC33FJ128MC706A-H/MR
DSPIC33FJ128MC706A-I/MR
DSPIC33FJ128MC706AT-E/MR
DSPIC33FJ128MC706AT-H/MR
DSPIC33FJ128MC706AT-I/MR
DSPIC33FJ256GP506A-E/MR
DSPIC33FJ256GP506A-I/MR
DSPIC33FJ256GP506AT-E/MR
DSPIC33FJ256GP506AT-I/MR
DSPIC33FJ32GS406-50I/MR
DSPIC33FJ32GS406-E/MR
DSPIC33FJ32GS406-I/MR
DSPIC33FJ32GS406T-50I/MR
DSPIC33FJ32GS406T-E/MR
DSPIC33FJ32GS406T-I/MR
DSPIC33FJ32GS606-50I/MR
DSPIC33FJ32GS606-E/MR
DSPIC33FJ32GS606-I/MR
DSPIC33FJ32GS606-I/MRC01
DSPIC33FJ32GS606T-50I/MR
DSPIC33FJ32GS606T-E/MR
DSPIC33FJ32GS606T-I/MR

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PCN_JAON-28MDOD807
CATALOG_PART_NBR
DSPIC33FJ32GS606T-I/MRC01
DSPIC33FJ64GP206A-E/MR
DSPIC33FJ64GP206A-I/MR
DSPIC33FJ64GP206AT-E/MR
DSPIC33FJ64GP206AT-I/MR
DSPIC33FJ64GP306A-E/MR
DSPIC33FJ64GP306A-I/MR
DSPIC33FJ64GP306AT-E/MR
DSPIC33FJ64GP306AT-I/MR
DSPIC33FJ64GP706A-E/MR
DSPIC33FJ64GP706A-I/MR
DSPIC33FJ64GP706AT-E/MR
DSPIC33FJ64GP706AT-I/MR
DSPIC33FJ64GS406-50I/MR
DSPIC33FJ64GS406-E/MR
DSPIC33FJ64GS406-I/MR
DSPIC33FJ64GS406T-50I/MR
DSPIC33FJ64GS406T-E/MR
DSPIC33FJ64GS406T-I/MR
DSPIC33FJ64GS606-50I/MR
DSPIC33FJ64GS606-E/MR
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DSPIC33FJ64GS606T-50I/MR
DSPIC33FJ64GS606T-E/MR
DSPIC33FJ64GS606T-I/MR
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DSPIC33FJ64MC506A-I/MR
DSPIC33FJ64MC506AT-E/MR
DSPIC33FJ64MC506AT-H/MR
DSPIC33FJ64MC506AT-I/MR
DSPIC33FJ64MC706A-E/MR
DSPIC33FJ64MC706A-I/MR
DSPIC33FJ64MC706AT-E/MR
DSPIC33FJ64MC706AT-I/MR
PIC24FJ128GA006-I/MR
PIC24FJ128GA106-E/MR
PIC24FJ128GA106-I/MR
PIC24FJ128GA106T-I/MR
PIC24FJ128GB106-I/MR
PIC24FJ128GB106T-I/MR
PIC24FJ192GA106-E/MR
PIC24FJ192GA106-I/MR

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PCN_JAON-28MDOD807
CATALOG_PART_NBR
PIC24FJ192GB106-I/MR
PIC24FJ256GA106-E/MR
PIC24FJ256GA106-I/MR
PIC24FJ256GA106T-E/MR
PIC24FJ256GA106T-I/MR
PIC24FJ256GB106-I/MR
PIC24FJ256GB106T-I/MR
PIC24FJ64GA006-I/MR
PIC24FJ64GA006T-I/MR
PIC24FJ64GA106-E/MR
PIC24FJ64GA106-I/MR
PIC24FJ64GA106T-I/MR
PIC24FJ64GA106T-I/MR029
PIC24FJ64GA106T-I/MR032
PIC24FJ64GA106T-I/MR033
PIC24FJ64GA106T-I/MR035
PIC24FJ64GB106-I/MR
PIC24FJ96GA006-I/MR
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PIC24HJ128GP206A-I/MR
PIC24HJ128GP206AT-E/MR
PIC24HJ128GP206AT-I/MR
PIC24HJ128GP306A-E/MR
PIC24HJ128GP306A-I/MR
PIC24HJ128GP306AT-E/MR
PIC24HJ128GP306AT-I/MR
PIC24HJ128GP506A-E/MR
PIC24HJ128GP506A-H/MR
PIC24HJ128GP506A-I/MR
PIC24HJ128GP506AT-E/MR
PIC24HJ128GP506AT-H/MR
PIC24HJ128GP506AT-I/MR
PIC24HJ256GP206A-E/MR
PIC24HJ256GP206A-I/MR
PIC24HJ256GP206AT-E/MR
PIC24HJ256GP206AT-I/MR
PIC24HJ64GP206A-E/MR
PIC24HJ64GP206A-I/MR
PIC24HJ64GP206A-I/MR031
PIC24HJ64GP206A-I/MRA28
PIC24HJ64GP206AT-E/MR
PIC24HJ64GP206AT-I/MR
PIC24HJ64GP206AT-I/MR031

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PCN_JAON-28MDOD807
CATALOG_PART_NBR
PIC24HJ64GP206AT-I/MRA28
PIC24HJ64GP506A-E/MR
PIC24HJ64GP506A-I/MR
PIC24HJ64GP506AT-E/MR
PIC24HJ64GP506AT-I/MR